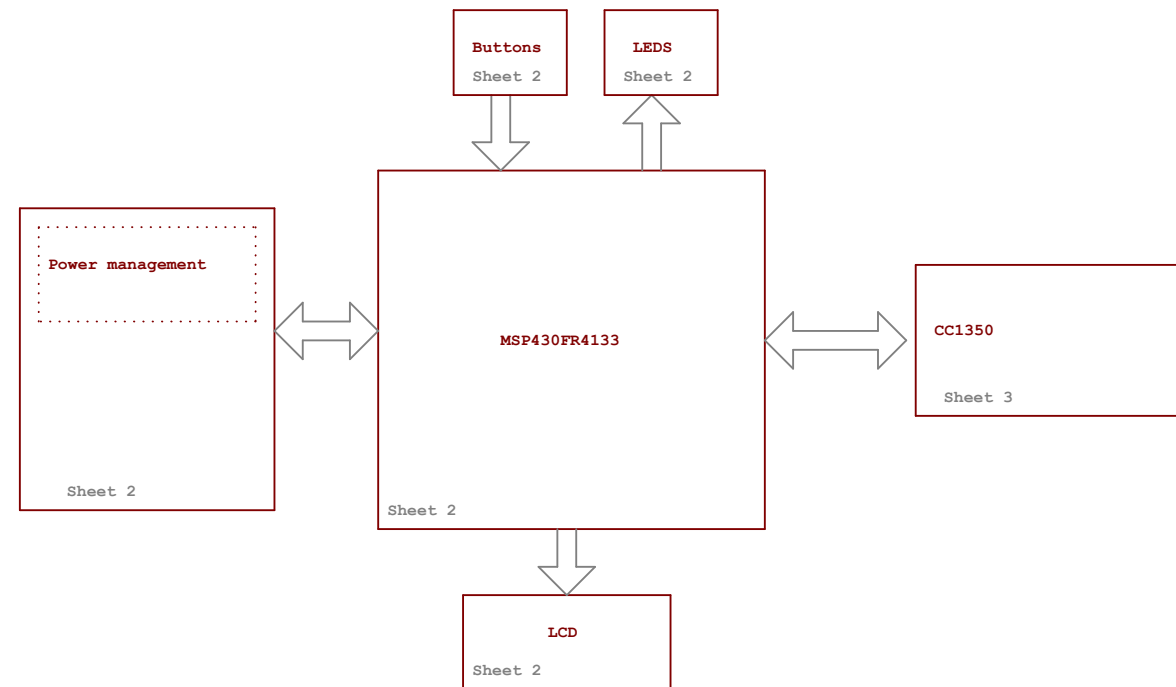



Revision History

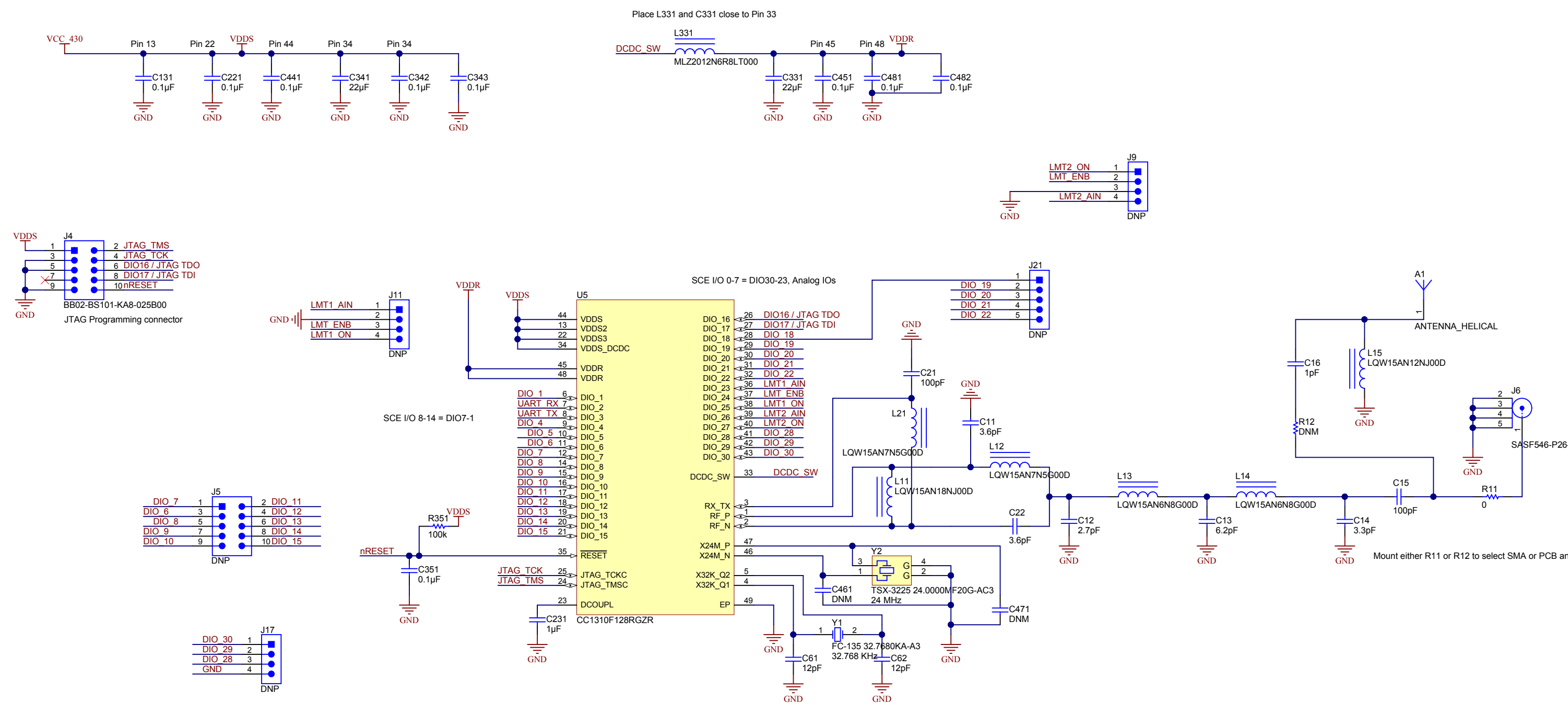
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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1.0

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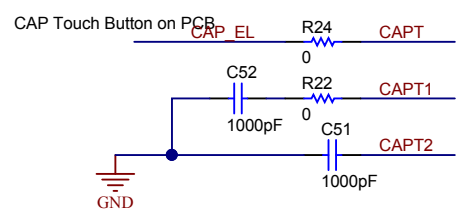
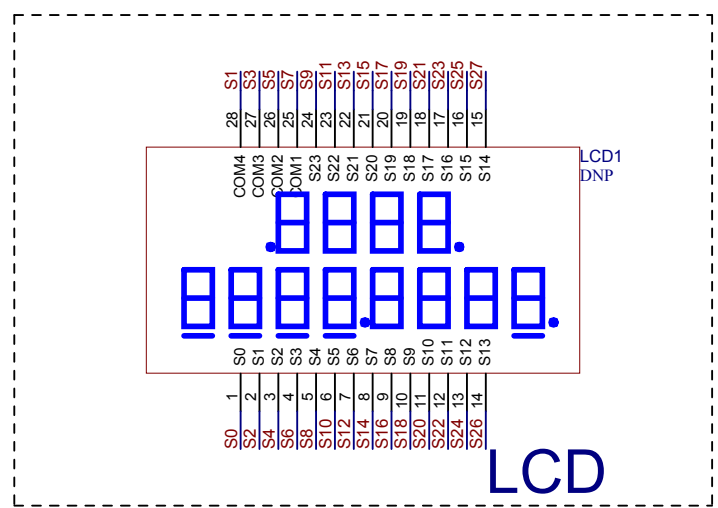
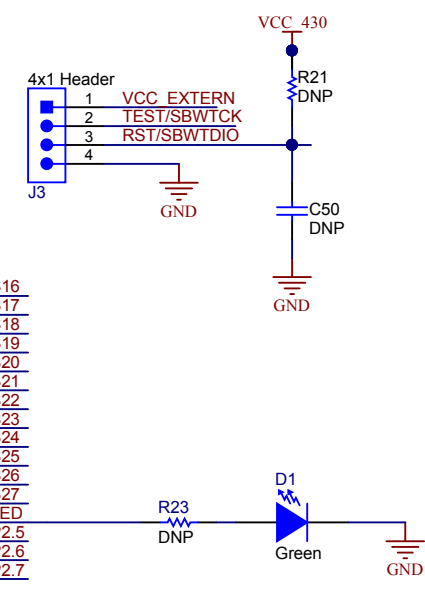
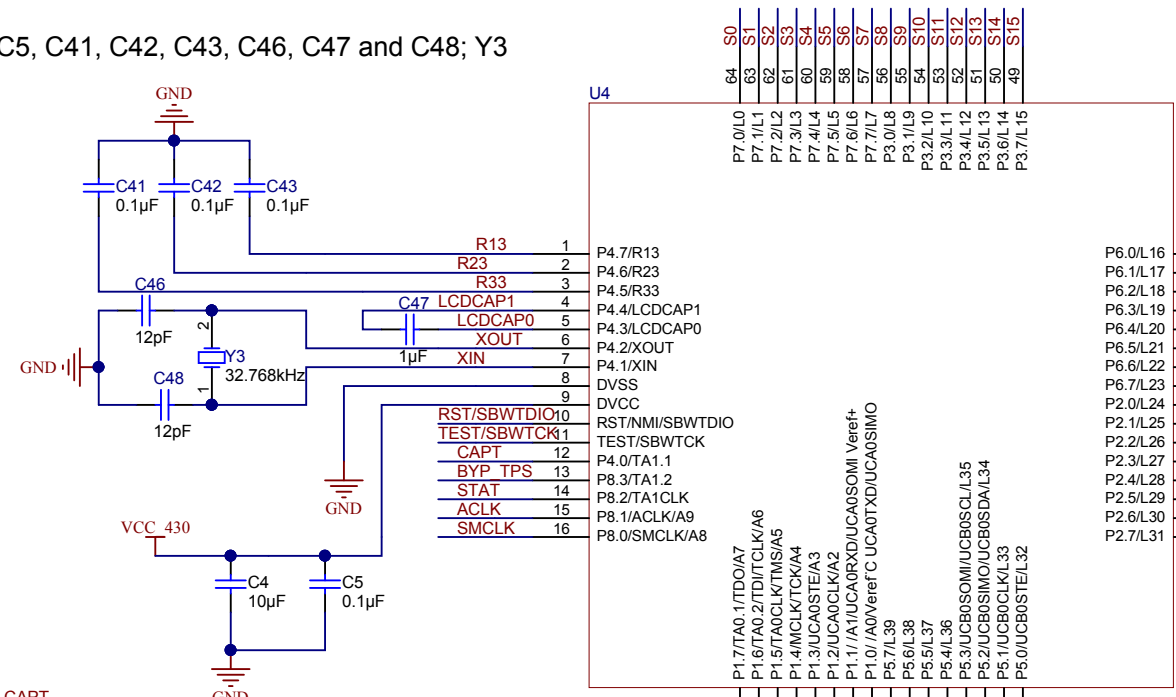
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Number: TIDA-00646	Rev: E1	Sheet: 1 of 3	
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By:	File: TIDA-00646-CoverSheet.SchDoc	Engineer: Milen Stefanov	Contact: http://www.ti.com/support



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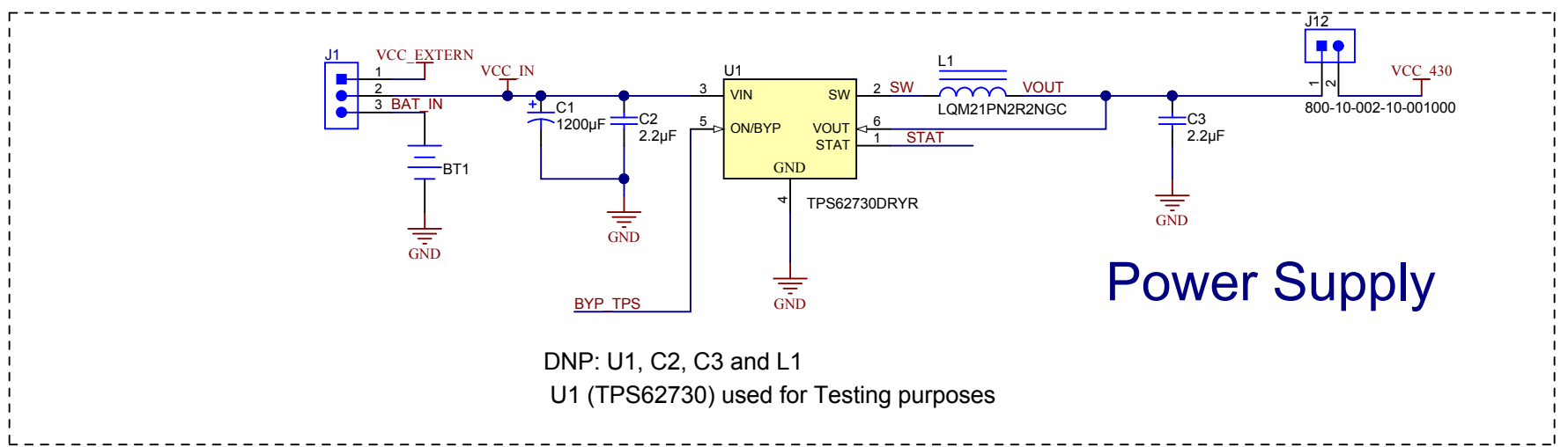
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Number: TIDA-00646	Rev: E1	File: TIDA-00646_RF.SchDoc	http://www.ti.com
SVN Rev: Version control disabled	Assembly Variant: 001	Contact: http://www.ti.com/support	© Texas Instruments 2015
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DNP: C4, C5, C41, C42, C43, C46, C47 and C48; Y3

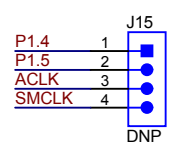
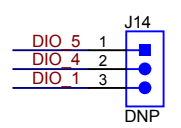
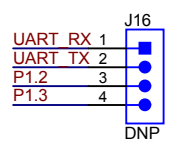
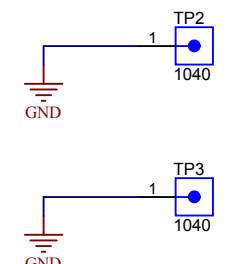
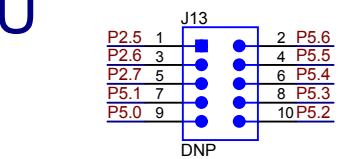


DNP: R22, R24, C51 and C52

Add jumper wire from J1-2 to J12-2 (to bypass the TPS62730)



DNP: U1, C2, C3 and L1
U1 (TPS62730) used for Testing purposes



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H1
NY PMS 440 0025 PH

H4
NY PMS 440 0025 PH

DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-00646
PCB Rev: E1

PCB
LOGO
Texas Instruments


PCB
LOGO
Pb-Free Symbol

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 10/18/2015	
TID #: TIDA-00646	Project Title: Matched Precision Temperature Sensing Reference	Sheet: 3 of 3	
Number: TIDA-00646	Rev: E1	Sheet Title:	http://www.ti.com
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By:	File: TID_Hardware.SchDoc	Contact: http://www.ti.com/support	
Engineer: Milen Stefanov			© Texas Instruments 2015

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